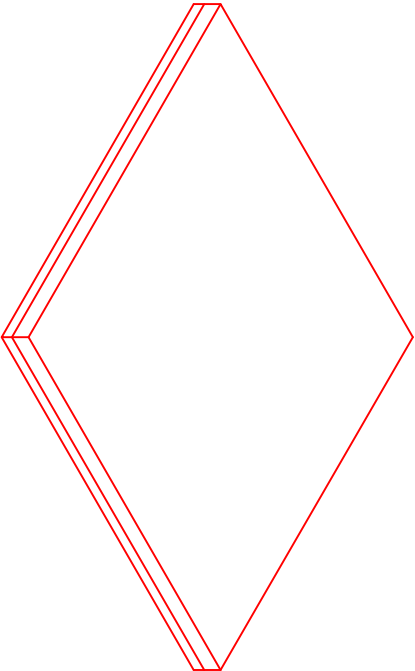


REV.	DESCRIPTION	DATE	CHECKED	COMPLETED BY
00	INITIAL RELEASE PER DCN C03427	04/03/98	E.B.	HLE
01	REVISED TOLERANCES, DCN C04602	09/03/98	E.B.	KUN

THE DIMENSIONS AND INFORMATION CONTAINED HEREIN ARE THE EXCLUSIVE PROPERTY OF AMKOR/ANALOG DEVICES. THIS DRAWING IS UNCLASSIFIED AND IS NOT TO BE RELEASED TO ANY THIRD PARTY WITHOUT THE EXPRESS WRITTEN PERMISSION OF AMKOR/ANALOG DEVICES.



7. REFERENCE SPECIFICATIONS:
A. AMKOR SPEC #001-0631-2294: PLACING OPERATION PROCEDURE.
B. AMKOR SPEC #001-0618-2082: MARKING.
6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.
- 5.
4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 100.
3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 10 X 10.
2. THE BASIC SOLDER BALL GRID PITCH IS 1.00.
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.
- NOTES: UNLESS OTHERWISE SPECIFIED

PRODUCTION				AMKOR Industrial Co., LTD.				AMKOR Electronics Inc.			
APPROVALS				DATE				TITLE			
R. GUERRERO				03/27/98				PACKAGE OUTLINE - CABGA 100, 11.00mm X 11.00mm, 2 LAYER, 1.00mm PITCH, LAMINATE SUBSTRATE, AAP			
M. EMLETTE				04/01/98				1.00mm PITCH, LAMINATE SUBSTRATE, AAP			
T. PANCAZAK				04/01/98				73634			
M. ANTONIO				04/03/98				SHEET 1 OF 3			